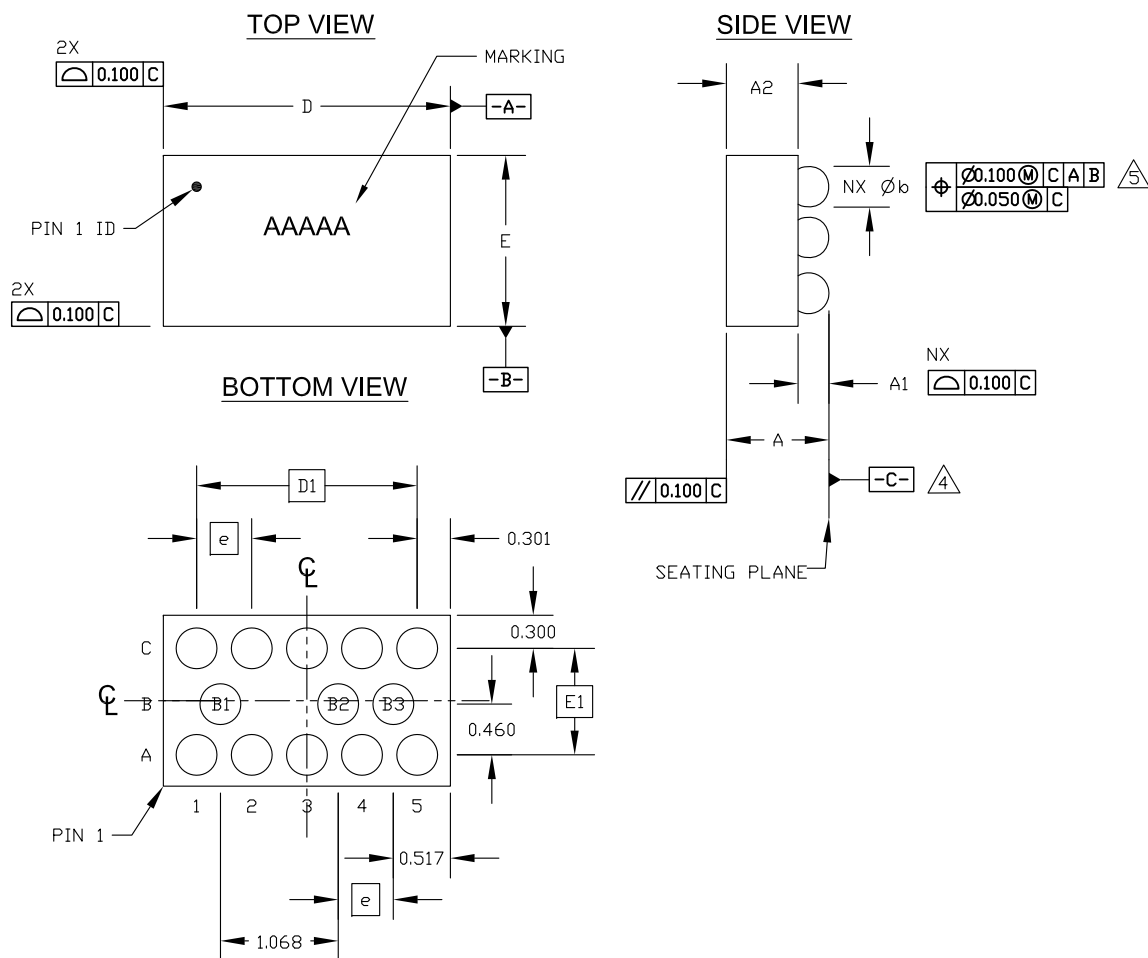




NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- MD IS THE BALL MATRIX SIZE IN THE "D" DIRECTION, ME IS THE BALL MATRIX SIZE IN THE "E" DIRECTION, AND N IS THE TOTAL NUMBER OF BALLS FOR THE MATRIX SIZE MD X ME AND DOES NOT INCLUDE BALLS FROM ANY DEPOPULATED LOCATIONS.
- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-2009.
- PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE CROWNS OF THE SOLDER BALLS.
- DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- THERE SHALL BE A MINIMUM CLEARANCE OF 0.10MM BETWEEN THE EDGE OF THE BUMP AND THE BODY EDGE.
- MARKING SHOWN IS FOR PKG. ORIENTATION PURPOSE ONLY.
- MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
- ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODES ONLY.

-DRAWING NOT TO SCALE-



TITLE:
PACKAGE OUTLINE, 13 BALLS
WLCSP, 0.50mm PITCH, C132A1+1

APPROVAL

DOCUMENT CONTROL NO.
21-0903

REV. A

1/1